

# KY-HGS 6140 Thermal potting adhesive

KY-HGS 6140 thermal conductivity potting adhesive is a medium and low viscosity additive silicone potting adhesive with excellent fluidity and stability. After mixing, it can be cured at room temperature or heated, with the higher the temperature, the faster the curing speed; This series of products in the curing reaction process does not produce any by-products, minimal shrinkage, with repairability, can be deeply cured into elastomers. In a wide range of temperature and humidity changes, it can reliably protect sensitive circuits and components for a long time, with excellent electrical insulation performance, can resist environmental pollution, avoid damage caused by environmental factors such as stress and vibration and humidity, especially suitable for two-wheeled three-wheelers and consumer lithium battery potting. This series of products has excellent physical and chemical resistance.

## Product feature

- Good fluidity, automatic leveling after mixing
- Good insulation properties
- There is no shrinkage and heat release after curing
- Soft elastomer after curing
- Excellent shock resistance
- Long time not congealing, loose and easy to agitate, excellent anti-settling and anti-caking

## Product application

- Ordinary electronic modules seal and conduct heat Transformer, ballast, inverter, relay
- Potting of electronic components and printed circuit boards
- Solar inverter charging pile module
- Network junction box

## Technical specification

| project                       |                       | unit              | component        |          |
|-------------------------------|-----------------------|-------------------|------------------|----------|
|                               |                       |                   | A                | B        |
| presolidification             | appearance            | /                 | grey             | White    |
|                               | viscosity             | cps               | 5000±500         | 5000±500 |
| Operational performance       | use ratio             | /                 | 1:1              |          |
|                               | Mixed viscosity       | cps               | 5000±300         |          |
|                               | operable time (25 °C) | min               | 60~90            |          |
|                               | oven heating (80°C)   | min               | 25±5             |          |
| postsolidification            | hardness              | shore A           | 65±5             |          |
|                               | Continuous use Temp   | °C                | -50 ~ 200        |          |
|                               | density               | g/cm <sup>3</sup> | 2.2±0.1          |          |
|                               | dielectric constant   | 1.2MHZ            | 3.0-3.3          |          |
|                               | mass resistivity      | Ω.cm              | 10 <sup>16</sup> |          |
|                               | dielectric strength   | KV/mm             | ≥20              |          |
|                               | fire resistance       | UL-94             | V0               |          |
| heat conductivity coefficient | W/m.k                 | 1.5±0.1           |                  |          |

\* The above performance data were all measured at 25°C and 55% relative humidity 1 day after forming. The company does not assume any responsibility for the different data caused by different test conditions or product improvement. The images may be different from the original products.

### ●Method of application

1, before mixing, first of all, the A component and B component in their respective containers fully stir.

2, when mixing, should comply with A component: B component = 1:1 weight ratio.

3. In general, products with a potting thickness below 20mm can naturally defoam, because the higher the temperature, the faster the curing speed will be

Speed up, for thicker products, can be defoamed according to needs. This is in order to remove the potting surface and internal production

The mixture should be put into a vacuum container and defrosted at -0.08MPa for at least 5 minutes.

4. The corresponding curing time should be maintained above the temperature given in the technical parameter table before and after curing, if the application thickness is relatively high

Thick, curing time may exceed. It can be cured at room temperature or by heating. The curing speed of the glue is affected by the curing temperature in winter

It takes a long time to cure, it is recommended to use heating curing, curing at 80°C for 30 minutes, under room temperature conditions generally need 8

Cure in about hours.

### ●Matters need attention :

1. After the operation is completed, the glue (unmixed) that A and B have not used up should be sealed and stored immediately. Stir well when using again.

2, in case of contact with skin, wipe clean, and then rinse with water; In case of contact with eyes, rinse immediately with water and remove

Hospital check.

### ●Storage and transportation :

1, this product is non-toxic non-dangerous goods, according to the general chemical handling and transportation can be

2, after use, pay attention to seal, store in a cool, dry, ventilated place.

3. The shelf life of this product is 12 months

## ●Packing specification

25Kg/ set (12.5Kg for A component + 12.5Kg for B component)

50Kg/ set (25Kg of Component A + 25Kg of component B)

600Kg/ set (A component 300Kg +B component 300Kg)

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